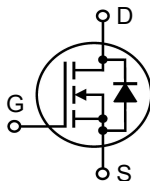


X3-Class HiPerFET™ Power MOSFET

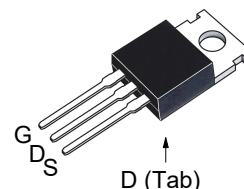
IXFP36N60X3

$V_{DSS} = 600V$
 $I_{D25} = 36A$
 $R_{DS(on)} \leq 90m\Omega$

N-Channel Enhancement Mode
Avalanche Rated



TO-220
(IXFP)



G = Gate D = Drain
S = Source Tab = Drain

| Symbol | Test Conditions | Maximum Ratings | |
|---------------|--|-----------------|------------|
| V_{DSS} | $T_J = 25^\circ C$ to $150^\circ C$ | 600 | V |
| V_{DGR} | $T_J = 25^\circ C$ to $150^\circ C$, $R_{GS} = 1M\Omega$ | 600 | V |
| V_{GSS} | Continuous | ± 20 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ C$ | 36 | A |
| I_{DM} | $T_C = 25^\circ C$, Pulse Width Limited by T_{JM} | 48 | A |
| I_A | $T_C = 25^\circ C$ | 8 | A |
| E_{AS} | $T_C = 25^\circ C$ | 750 | mJ |
| dv/dt | $I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$ | 50 | V/ns |
| P_D | $T_C = 25^\circ C$ | 446 | W |
| T_J | | -55 ... +150 | $^\circ C$ |
| T_{JM} | | 150 | $^\circ C$ |
| T_{stg} | | -55 ... +150 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering 1.6 mm (0.062 in.) from Case for 10s | 300 | $^\circ C$ |
| M_d | Mounting Torque | 1.13 / 10 | Nm/lb.in |
| Weight | | 3 | g |

Features

- International Standard Package
- Low $R_{DS(ON)}$ and Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

| Symbol | Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified) | Characteristic Values | | |
|--------------|---|-----------------------|------|--------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0V$, $I_D = 1mA$ | 600 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 2.5mA$ | 3.5 | | 5.0 V |
| I_{GSS} | $V_{GS} = \pm 20V$, $V_{DS} = 0V$ | | | ± 100 nA |
| I_{DSS} | $V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_J = 125^\circ C$ | | | 25 μA 1 mA |
| $R_{DS(on)}$ | $V_{GS} = 10V$, $I_D = 0.5 \cdot I_{D25}$, Note 1 | | | 90 m Ω |

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|-------------------------------------|---|-----------------------|------|-------------------------|
| | | Min. | Typ. | Max |
| g_{fs} | $V_{DS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1 | 16 | 26 | S |
| R_{Gi} | Gate Input Resistance | | 2.1 | Ω |
| C_{iss} | } $V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$ | | 2030 | pF |
| C_{oss} | | | 3050 | pF |
| C_{rss} | | | 3.6 | pF |
| Effective Output Capacitance | | | | |
| $C_{o(er)}$ | Energy related } $V_{GS} = 0\text{V}$ | | 110 | pF |
| $C_{o(tr)}$ | Time related } $V_{DS} = 0.8 \cdot V_{DSS}$ | | 510 | pF |
| $t_{d(on)}$ | } Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 10\Omega$ (External) | | 23 | ns |
| t_r | | | 8 | ns |
| $t_{d(off)}$ | | | 45 | ns |
| t_f | | | 4 | ns |
| $Q_{g(on)}$ | } $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ | | 29 | nC |
| Q_{gs} | | | 10 | nC |
| Q_{gd} | | | 10 | nC |
| R_{thJC} | | | | 0.28 $^\circ\text{C/W}$ |
| R_{thCS} | | 0.50 | | $^\circ\text{C/W}$ |

Source-Drain Diode

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|----------|--|-----------------------|------|---------------|
| | | Min. | Typ. | Max |
| I_S | $V_{GS} = 0\text{V}$ | | | 36 A |
| I_{SM} | Repetitive, Pulse Width Limited by T_{JM} | | | 144 A |
| V_{SD} | $I_F = I_S$, $V_{GS} = 0\text{V}$, Note 1 | | | 1.4 V |
| t_{rr} | } $I_F = 18\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$ | | 180 | ns |
| Q_{RM} | | | 1.6 | μC |
| I_{RM} | | | 18.0 | A |

Note 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

Littelfuse reserves the right to change limits, test conditions and dimensions.

| | | | | | | | | | | |
|---|-----------|-----------|-----------|-----------|-------------|-------------|-------------|-------------|-------------|-------------|
| IXYS MOSFETs and IGBTs are covered | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065B1 | 6,683,344 | 6,727,585 | 7,005,734B2 | 7,157,338B2 |
| by one or more of the following U.S. patents: | 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123B1 | 6,534,343 | 6,710,405B2 | 6,759,692 | 7,063,975B2 | |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728B1 | 6,583,505 | 6,710,463 | 6,771,478B2 | 7,071,537 | |

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

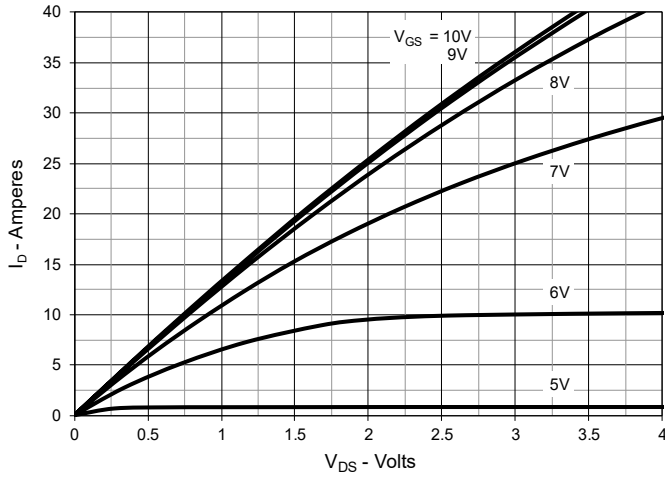


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

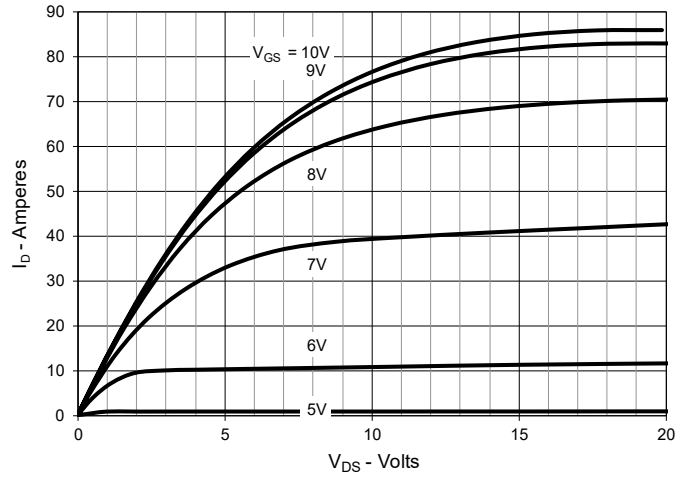


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

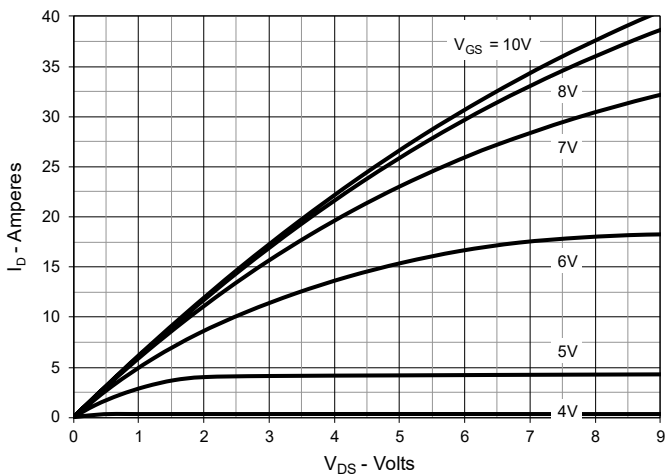


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 18\text{A}$ Value vs. Junction Temperature

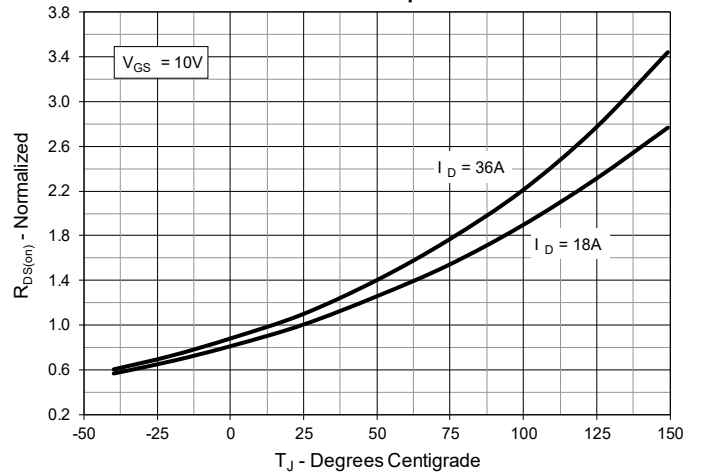


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 18\text{A}$ Value vs. Drain Current

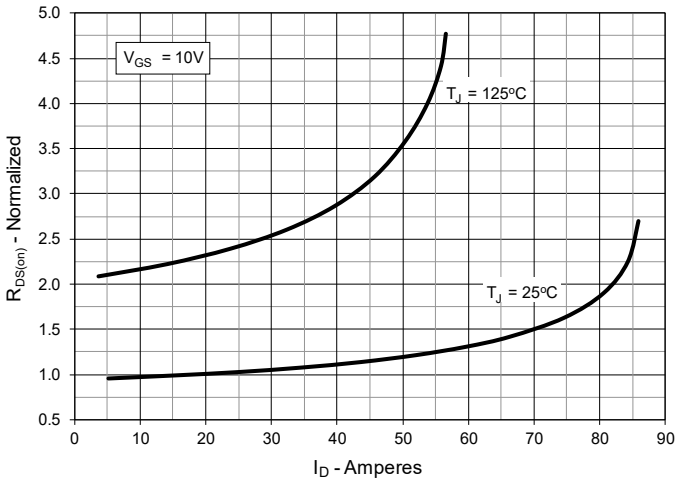


Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature

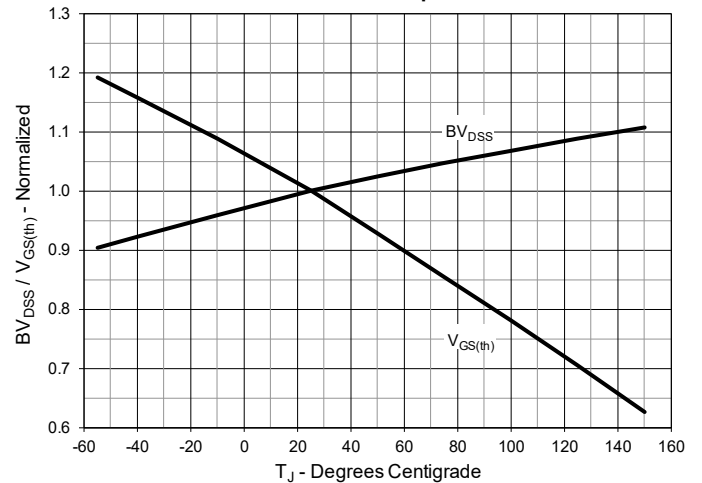


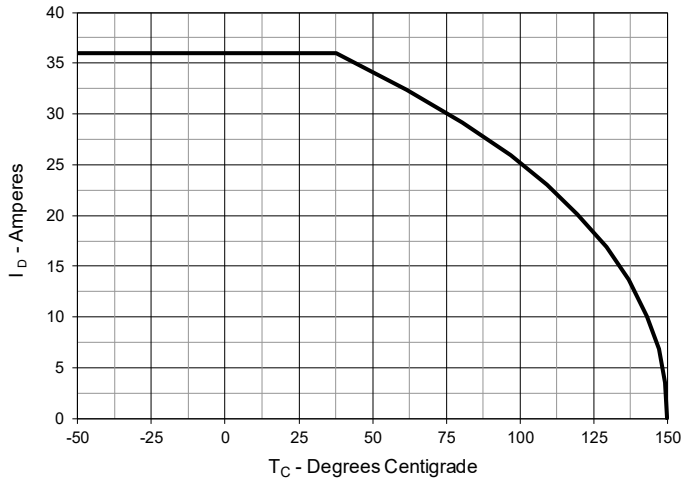
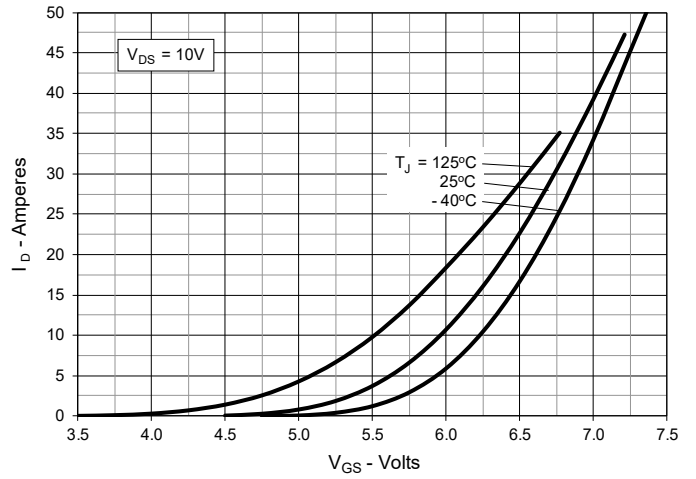
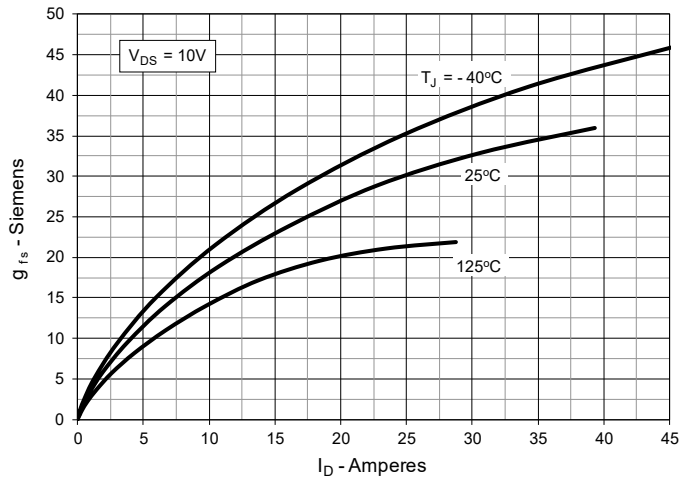
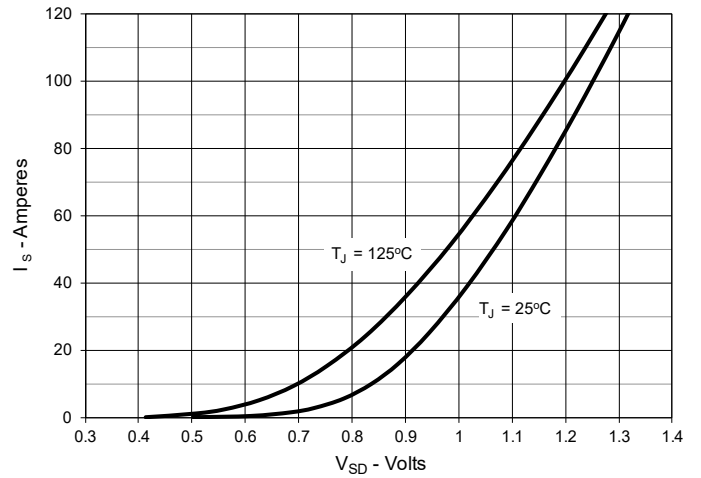
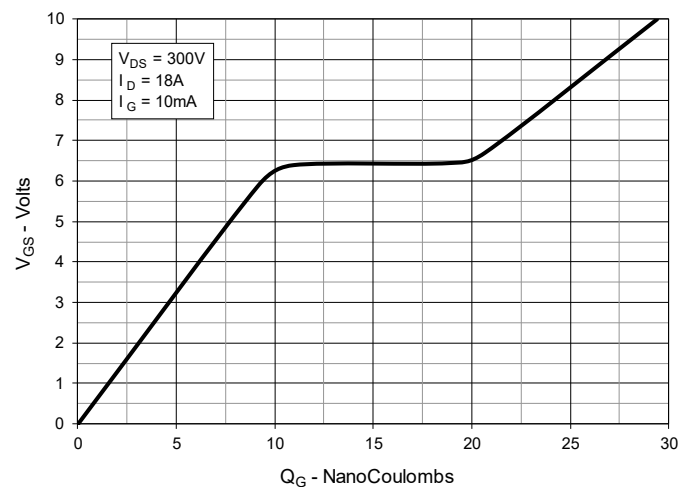
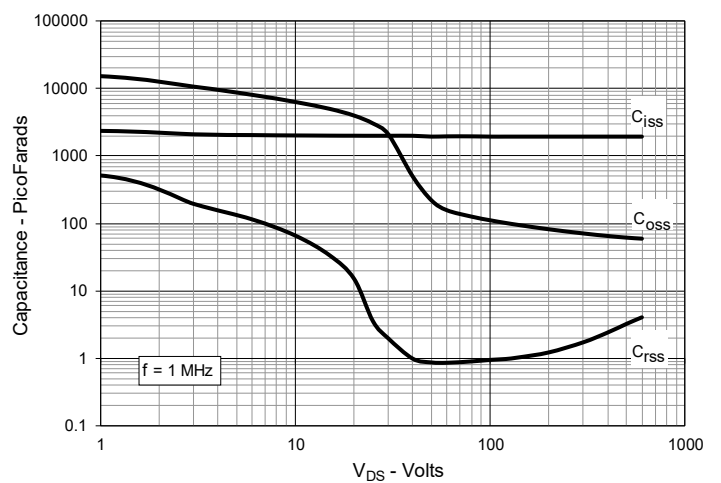
Fig. 7. Maximum Drain Current vs. Case Temperature

Fig. 8. Input Admittance

Fig. 9. Transconductance

Fig. 10. Forward Voltage Drop of Intrinsic Diode

Fig. 11. Gate Charge

Fig. 12. Capacitance


Fig. 13. Output Capacitance Stored Energy

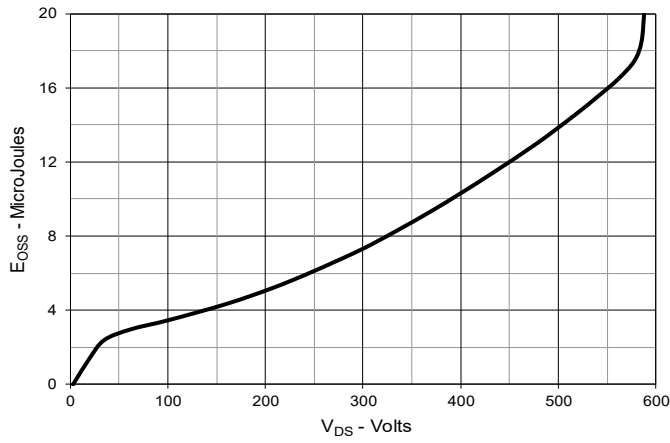


Fig. 14. Forward-Bias Safe Operating Area

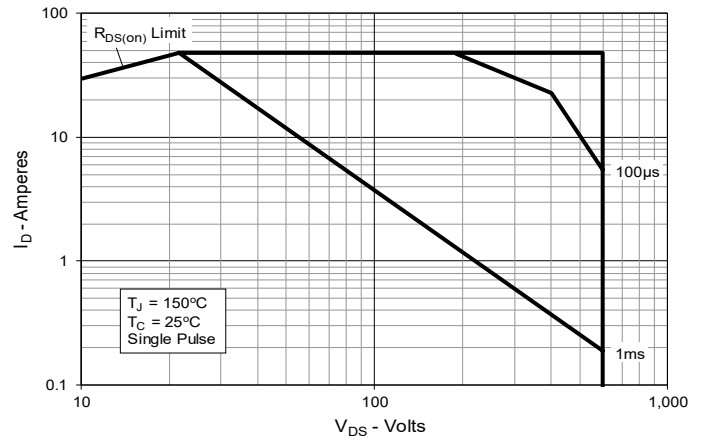
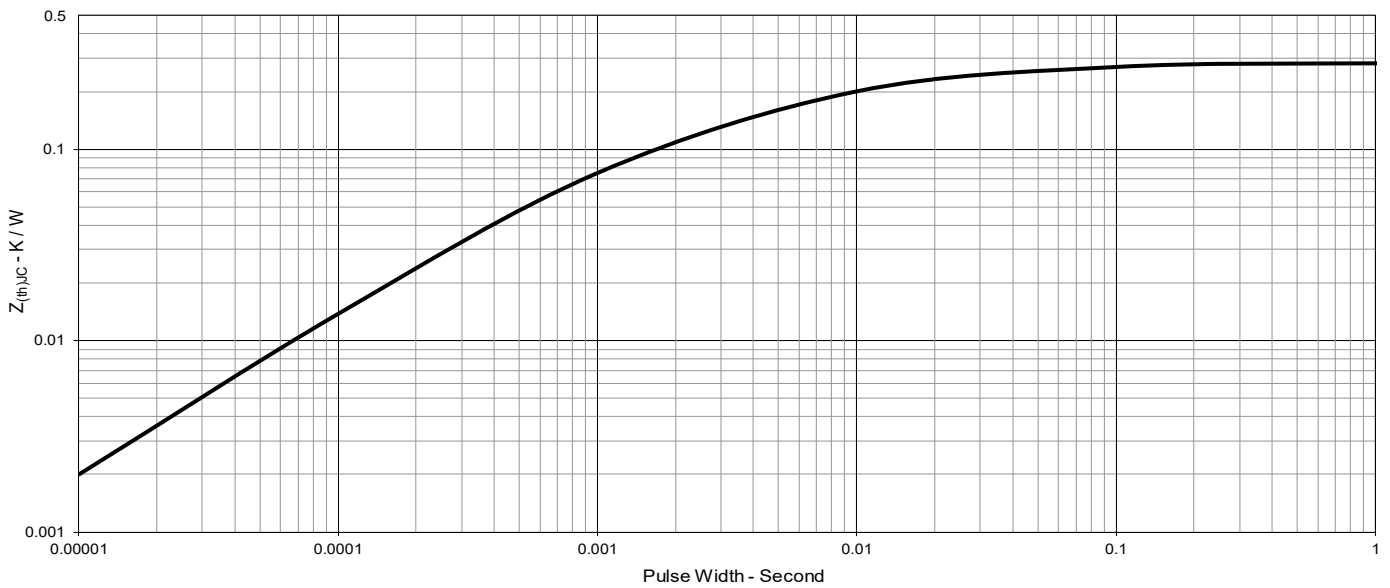
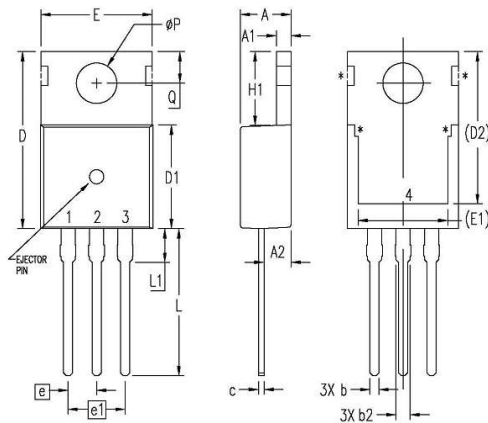


Fig. 15. Maximum Transient Thermal Impedance



TO-220 Outline



1 - Gate
2,4 - Drain
3 - Source

| SYM | INCHES | | MILLIMETERS | |
|------|----------|------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .169 | .185 | 4.30 | 4.70 |
| A1 | .047 | .055 | 1.20 | 1.40 |
| A2 | .079 | .106 | 2.00 | 2.70 |
| b | .024 | .039 | 0.60 | 1.00 |
| b2 | .045 | .057 | 1.15 | 1.45 |
| c | .014 | .026 | 0.35 | 0.65 |
| D | .587 | .626 | 14.90 | 15.90 |
| D1 | .335 | .370 | 8.50 | 9.40 |
| (D2) | .500 | .531 | 12.70 | 13.50 |
| E | .382 | .406 | 9.70 | 10.30 |
| (E1) | .283 | .323 | 7.20 | 8.20 |
| e | .100 BSC | | 2.54 BSC | |
| e1 | .200 BSC | | 5.08 BSC | |
| H1 | .244 | .268 | 6.20 | 6.80 |
| L | .492 | .547 | 12.50 | 13.90 |
| L1 | .110 | .154 | 2.80 | 3.90 |
| ØP | .134 | .150 | 3.40 | 3.80 |
| Q | .106 | .126 | 2.70 | 3.20 |

NOTE:

1. These dimensions do not include mold protrusion.
2. Metal finish - Matte pure tin plating except trim area.
3. Pin call out: 1 - GATE, 2 - DRAIN (COLLECTOR for IGBT), 3 - SOURCE (EMITTER for IGBT), 4 - DRAIN (Connected with #2 internally)
4. Ejector pin location & diameter will vary depending on packaging suppliers.
5. * marked area will vary depending on packaging suppliers.



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